

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TONGBI JIANG
EDWARD SCHROCK

Serial No.: 09/258,961

ART UNIT: 2811

Filing Date: March 1, 1999

99 APR 12 AM 11:33
TECHNOLOGY CENTER 2800

Title: METHOD FOR FABRICATING BGA
PACKAGE USING SUBSTRATE WITH
PATTERNEDE SOLDER MASK OPEN IN
DIE ATTACH AREA

Attorney Docket No.: 98-0645.1

RECEIVED

**REQUEST FOR CORRECTION ON THE FILING RECEIPT
MARCH 30, 1999**

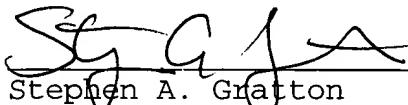
APPLICATION PROCESSING DIVISION'S
CUSTOMER CORRECTION BRANCH
Patent & Trademark Office
Washington, D.C. 20231

Dear Sir:

Enclosed for correction is the Filing Receipt for the
above application with the change noted thereon.

If any fees are due, the Commissioner is authorized to
deduct any fees from Deposit Account No. 07-1857. A
duplicate copy of this sheet is enclosed.

Respectfully submitted:


Stephen A. Gratton
Registration No. 28,418
Attorney for Applicant

2764 South Braun Way
Lakewood, CO 80228
(303) 989 6353

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: APPLICATION PROCESSING DIVISION'S CUSTOMER CORRECTION BRANCH, Patents and Trademark Office, Washington, D.C. 20231 on this 30th day of March, 1999.

March 30, 1999
Date of Signature


Stephen A. Gratton, Attorney for Applicants

FILING RECEIPT

APR 8 2 1999

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UNITED STATES DEPARTMENT OF COMMERCE
Patent and Trademark Office
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OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTORNEY DOCKET NO.	DRWGS	TOT CL	IND CL
09/258,961	03/01/99	2811	\$838.00	98-0645.1	6	13	4

STEPHEN A GRATTON
2764 SOUTH BRAUN WAY
LAKEWOOD CO 80228

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Application Processing Division's Customer Correction Branch within 10 days of receipt. Please provide a copy of the Filing Receipt with the changes noted thereon.

Applicant(s)

TONGBI JIANG, BOISE, ID; EDWARD SCHROCK, ~~BOISE~~, ID.

Boise

CONTINUING DATA AS CLAIMED BY APPLICANT-

THIS APPLN IS A CIP OF 09/191,215 11/12/98

IF REQUIRED, FOREIGN FILING LICENSE GRANTED 03/23/99

TITLE

METHOD FOR FABRICATING BGA PACKAGE USING SUBSTRATE WITH PATTERNED
SOLDER MASK OPEN IN DIE ATTACH AREA

PRELIMINARY CLASS: 257

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DATA ENTRY BY: HALL, ELMIRA

TEAM: 02 DATE: 03/23/99

FILE COPY



Bib Data Sheet



UNITED STATES DEPARTMENT OF
COMMERCE
Patent and Trademark Office

Address: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

SERIAL NUMBER 09/258,961	FILING DATE 03/01/1999 RULE	CLASS 257	GROUP ART UNIT 2811	ATTORNEY DOCKET NO. 98-0645.1
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APPLICANTS

TONGBI JIANG, BOISE, ID ;
EDWARD SCHROCK, BOISE, ID ;

** CONTINUING DATA ***

THIS APPLICATION IS A DIV OF 09/191,215 11/12/1998 PAT 6,048,755

** FOREIGN APPLICATIONS ***

IF REQUIRED, FOREIGN FILING LICENSE

GRANTED ** 03/23/1999

Foreign Priority claimed	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	STATE OR COUNTRY ID	SHEETS DRAWING	TOTAL CLAIMS	INDEPENDENT CLAIMS
35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance		6	13	4
Verified and Acknowledged	<i>John Farrell</i> Examiner's Signature	<i>M</i> Initials			

ADDRESS

STEPHEN A GRATTON
2764 SOUTH BRAUN WAY
LAKEWOOD, CO 80228

TITLE

BGA Package Having Substrate With Patterned Solder Mask Defining Open Die Attach Area

FILING FEE RECEIVED 838	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other <input type="checkbox"/> Credit
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**DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION
(Joint Inventors)**

We as the below named inventors, declare that:

Our residences, post office addresses and citizenships are as stated below next to our names.

We believe we are the original, first and joint inventors of the subject matter which is claimed and for which patent is sought on the invention entitled:

**METHOD FOR FABRICATING BGA PACKAGE USING SUBSTRATE
WITH PATTERNED SOLDER MASK OPEN IN DIE ATTACH AREA**

the specification of which (check one)

is attached hereto.

was filed on _____ as Application

Serial No. _____

and was amended on (if applicable) _____.

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Sec. 1.56(a).

We hereby claim foreign priority under Title 35, United States Code, Sec. 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: NONE

We hereby claim the benefit under Title 35, United States Code, Sec. 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Sec. 11, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Sec. 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application: NONE

POWER OF ATTORNEY: We hereby appoint as our attorneys, STEPHEN A. GRATTON, Registration No. 28,418; MICHAEL L. LYNCH, Registration No. 30,871; and LIA M. DENNISON, Registration No. 34,095, with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith. All correspondence and telephonic communications should be directed to:

STEPHEN A. GRATTON
2764 South Braun Way
Lakewood, CO 80228

Telephone: (303) 989 6353
Fax: (303) 989 6538

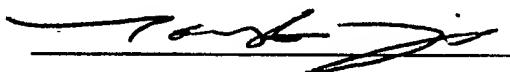
We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Wherefore, we pray that Letters Patent be granted to us for the invention or discovery described and claimed in the foregoing specification and claims, declaration, power of attorney, and this petition.

INVENTOR'S FULL NAME:

TONGBI JIANG

INVENTOR'S SIGNATURE:



11/6/98

DATE OF SIGNATURE:

RESIDENCE (CITY AND STATE)

Boise, Idaho

CITIZENSHIP:

P.R. China

POST OFFICE ADDRESS:

12036 W. Patrina Drive
Boise, ID 83713

INVENTOR'S FULL NAME: **EDWARD SCHROCK**

INVENTOR'S SIGNATURE: Edward Schrock

DATE OF SIGNATURE: 11-5-98

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Boise, ID 83716**